

ASmPT enabling the
digital world



Consumables

Boosting throughput and yield for the Intelligent Factory



Consumables

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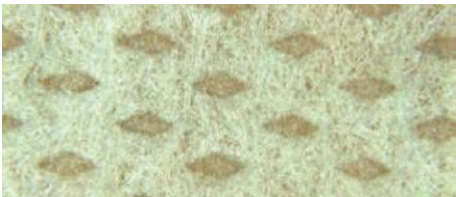
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The quality and stability of the printing process greatly impacts efficiency and yield for the entire SMT line. With increasing miniaturization and component diversity, the printing process has become more complex than ever before.

In order to optimize the printing operation and realize the best results technically possible, harmonization of printing equipment, stencils, squeegees, tooling solutions and consumables is required. As the leading print process expert, ASMPT is the world's only equipment supplier that offers a comprehensive portfolio of process support products (PSPs) which enhance printing on DEK platforms, as well as equipment made by other manufacturers.

DEK Ultra-Fine Pitch (UFP) ECO understencil cleaning rolls

DEK UFP ECO rolls are designed to boost productivity and yield, reduce defects and decrease manufacturing costs.



The unique 3D architecture of DEK UFP ECO understencil cleaning rolls counters the risk of contamination as the fabric traps solder paste and solders balls within its pockets. This is a key differentiator from paper-based products that allow paste to remain on the surface of the paper, creating the potential for contamination. Consequently, DEK UFP ECO rolls not only ensure effective understencil cleaning, they also prevent contamination-related defects.

Ideal for ultra-fine-pitch apertures inherent with today's miniaturized devices, DEK UFP ECO rolls ensure a quick and effective clean. The hydrophilic properties of the fibers provide fast wicking, as solvent is delivered through the fabric to the bottom of stencil instantaneously so that cleaning is more thorough and solvent consumption is reduced.

Features and benefits:

- Outstanding cleaning performance
- Reduced solvent consumption by an average of 50%
- Unique 3D structure traps solder particles away from the stencil, removing smear
- Ultra-low linting, Class 1000, ISO6 cleanroom compatible
- Enhanced vacuum performance
- Hydrophilic fiber structure for rapid solvent wicking
- ESD-safe packaging
- Improved process control
- Non-abrasive structure of fabric increases stencil and coating life
- Environmentally-friendly, chloride-free, recyclable
- Faster, more effective cleaning cycle leading to higher throughput

DEK UFP ECO UNDERSTENCIL CLEANING ROLLS							
Part number		Platform	Fabric width (mm)	Core width (mm)	Inner core diameter (mm)	Roll max outer diameter (mm)	Roll length (m)
SAP	DEK						
03128525	800071	ASMPT (DEK Micron)	515	530	19	56	11
03128531	800072	ASMPT (DEK Micron)	400	530	19	56	11
03130297	800073	ASMPT (DEK Micron)	300	530	19	56	11
03239913	—	ASMPT (DEK TQ)	400	—	—	—	19
03128585	800074	MPM	443	457	19.5	64	12
03131628	800075	MPM	443	457	19.5	100	44
03131629	800076	MPM	546	559	19.5	64	12
03131630	800077	EKRA	400	400	13	53	10
03131631	800078	EKRA	500	500	13	53	10
03131632	800080	Panasonic	365	380	19.5	64.5	15
03131633	800082	Yamaha	440	440	25.5	88	25
03131634	800083	Yamaha	530	530	25.5	88	25
03155072	800084	Yamaha	620	620	25.5	88	25

DEK SMT high performance understencil cleaning fabrics

DEK SMT high-performance understencil cleaning fabrics provide effective cleaning and compatibility with multiple print platforms.



Features and benefits:

- Absorbent, vacuum-friendly & fast-wicking
 - Special non-woven fabric construction reduces lint, preventing aperture blockages and contamination
 - Fabric does not compromise vacuum power, optimizing aperture cleaning performance
 - Wicks consistently across the full width of the cleaning roll to ensure even distribution of the cleaning agent for a more productive clean
 - Wick time is extremely fast compared to other cleaning fabrics
- Effective cleaning
 - Dry cycle in addition to Wet (Vac/Dry) cycle
 - Delivers a superior clean for underside of the stencil
- Broad machine compatibility
 - Suitable for ASMPT, MPM, Ekra and other on-board cleaning systems, in addition to advanced understencil cleaners
 - 11 meters minimum length reduces number of changeovers and total changeover time on DEK platforms
 - 44 meter length available for latest MPM platform

DEK SMT HIGH PERFORMANCE UNDERSTENCIL CLEANING FABRICS							
Part number		Platform	Fabric width (mm)	Core width (mm)	Roll diameter (mm)	Inner core (mm)	Roll length (m)
SAP	DEK						
03127081	176215	ASMPT (DEK Micron)	515	530	56	19	11
03128524	176216	ASMPT (DEK Micron)	400	530	56	19	11
03128532	176217	ASMPT (DEK Micron)	300	530	56	19	11
03128523	173826*	ASMPT (DEK Micron)	515	530	56	19	11
03128538	431524	ASMPT (DEK Micron)	607	620	56	19	11
03233780		ASMPT (DEK Micron)	625				11
03144917	431424	ASMPT (DEK Micron for Typhoon)	300	325	56	19	11
03217296	–	ASMPT (DEK TQ)	420	–	–	–	~ 22
03252411	–	ASMPT (DEK TQ L)	515	–	–	–	22
03252072	–	ASMPT (DEK TQ L)	580	–	–	–	22
03131502	173451	AP series, UP series, SPM, MPM125, Accela, Momentum	320	457	64	19	12
03131501	173450	AP series, UP series, SPM, MPM125, Accela, Momentum	443	457	64	19	12
03139825	178911	AP series, UP series, SPM, MPM125, Accela, Momentum	597	622	64	19	12
03131512	178864	Accela, Momentum	443	457	100	19	44
03144221	178909	Accela, Momentum	546	559	100	19	44
03128533	178908	All Ekra In - Line printers	400	400	53	13	10
03131513	178907	All Ekra In - Line printers	500	500	53	13	10
03131611	431556	All Ekra In - Line printers	500	500	53	13	8

*With metalised anti-static packaging.

DEK Pro and DEK Pro XF advanced understencil cleaning chemistries

Designed specifically for understencil cleaning, DEK Pro and DEK Pro XF improve process performance and reduce print defects. They are safer, cleaner and more environmentally friendly than IPA and traditional solvent cleaners, and are compliant with all industry standards and environmental regulations.



Features and benefits:

- Prioritizes health, safety and the environment
 - DEK Pro XF has no flash point and is low VOC
 - DEK Pro has a high flash point of 67° C (IPA flash point is 12° C)
 - Safer to use, transport, store and dispose
 - Manufactured using biodegradable materials
- Reduce print defects
 - No impact on thixotropic properties of the solder paste
 - Reduce risk of solder slump and solder balling
 - Residue-free after evaporation
- Compliant and compatible
 - Compatible with all solder paste materials
 - RoHS and REACH compliant

DEK PRO ADVANCED UNDERSTENCIL CLEANING CHEMISTRIES				
Part number		Description	Volume	Available for
SAP	DEK			
03129706	173483	DEK Pro cleaning agent	1 liter	Vacuum and non vacuum printers and manual cleaning
03129708	173485	DEK Pro cleaning agent	5 liters	Vacuum and non vacuum printers and manual cleaning
03130223	431093	DEK Pro cleaning agent	20 liters	Vacuum and non vacuum printers and manual cleaning

DEK PRO XF ADVANCED UNDERSTENCIL CLEANING CHEMISTRIES				
Part number		Description	Volume	Available for
SAP	DEK			
03130225	431513	DEK Pro XF cleaning agent	1 liter	Vacuum printers
03126194	431514	DEK Pro XF cleaning agent	5 liters	Vacuum printers

Pre-saturated wipes

Designed for fast and effective cleaning of stencil surfaces, adhesives and general cleaning applications, pre-saturated cleaning wipes are ideal for quick clean-up on the line.



comprised of 70% Isopropyl alcohol and 30% de-ionized water and is excellent for removal of fluxes, light oils, polar soils and white mineral residue.

NEW: DEK IPA/DI 96% wipes

New IPA 96% wipes for even lower residue, even faster evaporation pre-saturated wipes are ideal for general cleaning applications. The cleaning solution is comprised of 96% Isopropyl alcohol and 4% de-ionized water and is excellent for removal of fluxes, light oils, polar soils and white mineral residue.

DEK Hand cleaner wipes

Pre-saturated, disposable DEK Hand cleaner wipes are designed for use in any environment where cleanliness is required for handling critical components. The environmentally-safe, citrus-scented, low-linting wipes are easily dispensed and dry quickly after application.

DEK IPA/DI wipes

DEK low-residue, rapid evaporation pre-saturated wipes are ideal for general cleaning applications. The cleaning solution is

DEK Stencil cleaner wipes

Designed for fast, efficient surface cleaning of stencils and screens, DEK Stencil cleaner wipes are non-abrasive and pre-saturated with hydro-treated Naphtha, which effectively cleans most commercial solder pastes and inks.

DEK Adhesive remover wipes

DEK Adhesive remover wipes clean adhesives from the surface of stencils and screens. Specifically designed for use in SMT processes, the wipes are compatible with most commercial adhesives.

DEK HAND CLEANER WIPES				
Part number		Description	Unit	Box quantity
SAP	DEK			
03128534	115809	Hand clean wipes, 1 tub contains 100 wipes	Per tub	6 tubs
03132440	173280	Hand clean wipes refill, 1 pack contains 100 wipes	Per pack	10 packs

DEK IPA/DI WIPES (70 % ISOPROPYL ALCOHOL 30% DE-IONISED WATER)				
Part number		Description	Unit	Box quantity
SAP	DEK			
03126895	115806	IPA/DI wipes, 1 tub contains 100 wipes	Per tub	6 tubs
03129703	173277	IPA/DI wipes refill, 1 pack contains 100 wipes	Per pack	10 packs

DEK IPA/DI WIPES 96-4 (96% ISOPROPYL ALCOHOL 4 % DE-IONISED WATER)				
Part number		Description	Unit	Box quantity
SAP	DEK			
03178114	-	IPA/DI 96% wipes, 1 tub contains 100 wipes	Per tub	6 tubs
03178115	-	IPA/DI 96% wipes refill, 1 pack contains 100 wipes	Per pack	10 packs

DEK STENCIL CLEANER WIPES				
Part number		Description	Unit	Box quantity
SAP	DEK			
03128526	115807	Stencil clean wipes, 1 tub contains 100 wipes	Per tub	6 tubs
03132439	173278	Stencil clean wipes refill, 1 pack contains 100 wipes	Per pack	10 packs

DEK ADHESIVE REMOVER WIPES				
Part number		Description	Unit	Box quantity
SAP	DEK			
03126751	115808	Adhesive remover wipes, 1 tub contains 100 wipes	Per tub	6 tubs
03128535	173279	Adhesive remover wipes refill, 1 pack contains 100 wipes	Per pack	10 packs

Cleaning sprays

ASMPT’s maintenance cleaners have been designed to facilitate convenient cleaning of electronics assembly applications for improved productivity at the lowest possible cost.



DEK SMT stencil cleaner

A powerful and versatile, non-corrosive and residue-free cleaner suitable for stencils, webbing, frames and misprinted boards, DEK SMT stencil cleaner’s hybrid formulation blends safe and non-flammable water-based ingredients with aggressive long-chain alcohol solvents.

Applications:

- Solder pastes, epoxies and inks
- Manual cleaning
- Automated understencil wipes
- Unheated ultrasonic cleaning systems
- Cold dip tanks
- Safe on all metals, synthetics, plastics and elastomers

DEK SMT STENCIL CLEANER			
Part number		Description	Unit
SAP	DEK		
03129695	173009	Can 470 ml (340 g/12 oz), standard case quantity 10 cans	Each
03134003	173042	1 US gallon (4 liters) refill	Each



DEK Reflow oven cleaner

This robust cleaner is a high-performance mix of water, alkaloids and long-chain alcohols to remove burned-on fluxes and residues. The DEK Reflow oven cleaner formulation uses residual oven heat to boost cleaning power, reducing cleaning time by as much as 50 % and preventing flux curing. The cleaner is non-flammable, quick-drying and ozone-safe.

Applications:

- Wave soldering machines
- Relow ovens
- Pick and place systems
- Metal pallets
- Heating elements
- Baffles & clamps
- Chains, pulleys, drive gears and housings

DEK REFLOW OVEN CLEANER			
Part number		Description	Unit
SAP	DEK		
03134011	173012	Can 470 ml (340 g/12 oz), standard case quantity 10 cans	Each
03134002	173045	1 US gallon (4 liters) refill	Each

Gloves



DEK Latex gloves

Powder-free, polymer-coated, latex gloves combine economical single use protection from most acids and bases with comfort and flexibility. The proprietary Miracle Grip polymer coating offers a significantly enhanced wet/dry grip with excellent sensitivity.

Features and benefits:

- Comfort, tactile sensitivity and ergonomic fit
- Go on easily, minimize skin-latex contact
- Maximize wet or dry grip
- Resist roll down
- Meet recognized tests and regulatory requirements

DEK LATEX GLOVES			
Part number		Description	Unit
SAP	DEK		
03134009	173015	9" polymer coated latex glove/MED	Bag 100
03134008	173016	9" polymer coated latex glove/LG	Bag 100
03134010	173017	9" polymer coated latex glove/XL	Bag 100



DEK Powder-free blue nitrile gloves

The affordable choice for consistency, performance and reliability, DEK nitrile gloves are manufactured to ensure a tough, durable glove, free of chemical odors and harsh, irritating deodorants. Stronger than either comparable latex or PVC/vinyl gloves, blue nitrile gloves provide excellent splash and contact protection from a wide range of chemicals. Textured palms and fingers offer exceptional wet or dry grip.

Features and benefits:

- Pure, 100 % nitrile polymer; absolutely no natural rubber latex proteins
- Medical grade for top performance
- Comfortable – flexible silky feel eliminates the tiring, constant hand pressure of latex gloves
- Rugged – three times more puncture resistant than vinyl or natural rubber latex gloves of equal thickness
- Economical – outperforms PVC and latex for reduced overall glove consumption

DEK POWDER-FREE BLUE NITRILE GLOVES			
Part number		Description	Unit
SAP	DEK		
03134006	173018	9" powder free blue nitrile glove/SM	Box 100
03134005	173019	9" powder free blue nitrile glove/MED	Box 100
03129696	173020	9" powder free blue nitrile glove/LG	Box 100
03134004	173021	9" powder free blue nitrile glove/XL	Box 100

High-purity precision cleaning dry wipes

DEK wipes feature non-woven and polyester technologies to maximize effectiveness and prevent contamination. They are designed, manufactured and packaged with precision to serve various cleaning and maintenance requirements.



DEK Non-woven material wipes

DEK Non-woven material wipes are made from a unique blend of cellulose and polyester to provide maximum absorbency, low particle generation and affordability. Most of the DEK Non-woven wipes are packaged in a cleanroom for use in Class 100 applications.

DEK Polyester material wipes

DEK Polyester material wipes are perfect for cleanroom applications – including optical work. The wipes are pre-cut and packaged in a cleanroom for use in Class 10 environments. Polyester wipes provide superior scrubbing capability with no lint left behind.

DEK HIGH-PURITY PRECISION CLEANING DRY WIPES			
Part number		Description	Unit
SAP	DEK		
03134066	115825	Wipes, med absorb, poly blend (15 x15 cm)	Bag 50
03134065	115826	Wipes, med absorb, poly blend (23 x 23 cm)	Bag 300
03134063	115829	Wipes, quilted absorb, (20 x 20 cm)	Bag 100
03134062	115832	Wipes, optical cleanroom poly (23 x 23 cm)	Bag 150
03130306	431088R	Cleanroom dry wipes 23 x 23 cm / 9" x 9"	Bag 150

Precision swabs

DEK Precision swabs are designed, manufactured and packaged to provide high-quality, economical solutions for various cleaning and maintenance requirements in SMT and clean room applications, or anywhere that cleaning is directly related to accuracy.



DEK Precision swabs have tips that are heat-sealed to the handles to avoid contamination and adhesive compatibility issues. The materials have been selected to provide the best flexibility and durability.

DEK Foam swabs

The foam swab is an excellent general-purpose swab for cleaning small and confined areas. Its laundered foam head possesses good absorbing capacity and cushioning. A compact, rigid handle and round internal head core provide firm support.

DEK PRECISION SWABS			
Part number		Description	Unit
SAP	DEK		
03134060	115840	Swab, foam LG. PDLE. HD 16 x 25 mm, L-13 cm	Bag 50
03134059	115841	Swab, foam SLM - HD 12 x 25 mm, L-12 cm	Bag 50
03134058	115842	Swab, foam NRW - HD 4 x 12 mm, L- 9 cm	Bag 50
03134057	115843	Swab, foam MED - HD 6 x 19 mm, L-11 cm	Bag 50
03128530	431415	Cleanroom foam swab, ESD handle	Bag 25
03128545	431416	Cleanroom foam swab, ESD handle	Bag 100

DEK Spatulas

DEK Spatulas are color-coded to ensure isolated use with appropriate materials and are an essential tool on the line. Light and durable, the polypropylene spatulas are shatterproof and flexible for long-lasting performance.



Features and benefits:

- Constructed of durable polypropylene
- Shatterproof and flexible
- Easy to grip
- Less likely than metal spatulas to scratch the stencil surface
- Easily cleaned with DEK pre-saturated wipes
- Wide blade width for more efficient clearing of solder paste

Available in two, color-coded versions:

- Lead-free green
- Anti-static black

DEK SPATULAS			
Part number		Description	Unit
SAP	DEK		
03128559	173788	Green spatula	Bag of 5
03129776	173825	Black ESD spatula	Bag of 5

DEK Solder paste nozzles

DEK Solder paste nozzles have been designed to facilitate solder paste cartridge changeover more cleanly and efficiently than conventional re-usable nozzles.



DEK Solder paste nozzles easily snap into place, making the cartridge immediately ready for use with on-board printer auto-dispense technologies. These easy-to-use nozzles eliminate clean-up of internal threads and solder paste drip, which are common side effects of threaded dispense tip installation.

With this unique design, manufacturers can reduce process costs, lower material waste and limit operator intervention.

Features and benefits:

- Color-coded: Visual identification of leaded and lead-free solder pastes.
- Non-drip: Paste flow is more controlled and excess material reduced; 'X' low profile promotes paste mixing during solder bead deposition.
- Disposable: Simple, reduced-cost nozzles can be disposed of with the empty solder paste tube. Eliminates messy, time-consuming nozzle changes. Compatible with SEMCO® type paste tubes.
- Low waste and anti-mix strategy compliant: Compact format reduces the amount of paste 'in transit' through the nozzle. Disposable design ensures no cross contamination of paste types.

DEK SOLDER PASTE NOZZLES			
Part number		Description	Unit
SAP	DEK		
03131635	800120	Paste nozzles green (lead-free)	500
03131636	800125	Paste nozzles red (lead-rich)	500
03128678	800121	Paste nozzles green evaluation pack	25
03128629	800126	Paste nozzles red evaluation pack	25
03153616	-	Paste nozzles black for jar dispenser	25

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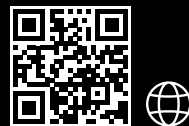
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